

AMENDMENT UNDER 37 C.F.R. § 1.111  
U.S. Application No. 09/664,094

3. (Amended) A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 2, wherein the size of said at least one hole formed in said ground plate is determined such that the AC coupling between the signal line and another signal line disposed close to the signal line and on the opposite side of said ground plate is decreased and the characteristic impedance of said signal transmission line is increased.

4. (Amended) A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 2, wherein the number of said at least one hole formed in said ground plate is determined such that the AC coupling between the signal line and another signal line disposed close to the signal line and on the opposite side of said ground plate is decreased and the characteristic impedance of said signal transmission line is increased.

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5. (Amended) A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate, wherein at least one hole is formed in both of said signal line and said ground plate.

6. (Amended) A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 5,

wherein the size of said at least one hole formed in said ground plate among the signal line and the ground plate is determined such that the AC coupling between the signal line and another signal line disposed close to the signal line and on the opposite side of said ground plate is decreased and the characteristic impedance of said signal transmission line is increased.

7. (Amended) A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 5, wherein the number of said at least one hole formed in said ground plate among holes formed in both of the signal line and the ground plate is determined such that the AC coupling between the signal line and another signal line disposed close to the signal line on the opposite side of said ground plate is decreased and the characteristic impedance of said signal transmission line is increased.

8. (Amended) A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 2, wherein said at least one hole in said ground plate is formed at a position where the other signal line is not disposed or said at least one hole in said ground plate is made small so as to reduce the AC coupling with one signal line when formed at a position where the other signal line is disposed.

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9. (Amended) A semiconductor integrated circuit comprising a signal transmission line of a microstrip structure comprising a signal line and a ground plate according to claim 1, wherein, instead of at least one hole formed in said signal line or in said ground plate, a plurality of slit holes are formed by forming said signal line or said ground plate of a plurality of thin strips and by connecting these thin strips at those terminal ends.